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ABSTRACT

The invention relates to a chip/a substrate (1) with multiple contact elements/surfaces (3) for producing an electrically conductive connection between a chip (1) and a substrate, especially by means of ultrasonic welding, whereby on the side of the chip/substrate (1) turn toward the substrate/chip, between the contact elements/surfaces (3) at least regionally an especially ultrasonically weldable bonding material (2) is arranged. The invention also concerns a method of bonding a chip (1) with a substrate, in which between the contact elements (3) of the chip (1) and the corresponding contact elements (3)/contact surfaces of the substrate, an ultrasonic welding connection is produced, whereby a bonding material applied between the contact elements (3) of the chip (1) and/or between the contact surfaces of a substrate, a further bond is produced between the substrate and the chip (1).

FIG. 2